

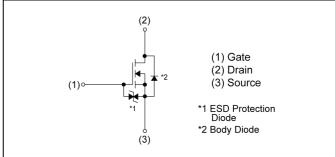
RJ1P12BBD

Nch 100V 120A Power MOSFET

V _{DSS}	100V
R _{DS(on)} (Max.)	5.8mΩ
Ι _D	±120A
P _D	178W

Outline TO-263AB (2)LPT(L)

Inner circuit



Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TLL
	Marking	RJ1P12BBD

● Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

U (a		• /		
Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	100	V
Continuous drain current V _{GS} = 10V		۱ _D *1	±120	А
Pulsed drain current	ا _{DP} *2	±240	А	
Gate - Source voltage	V _{GSS}	±20	V	
Avalanche current, single pulse	I _{AS} *3	40	А	
Avalanche energy, single pulse	E _{AS} *3	125	mJ	
Power dissipation	P _D ^{*1}	178	W	
Junction temperature	Tj	150	C°	
Operating junction and storage temper	T _{stg}	-55 to +150	C°	

5) Halogen free

1) Low on - resistance

2) High power small mold package

3) Pb-free lead plating ; RoHS compliant

Application

Features

4) UIS tested

Switching

•Thermal resistance

Parameter	Symbol	Values			Linit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*1}	-	-	0.70	°C/W

•Electrical characteristics (T_a = 25°C)

Demonster	Oursela e l	Q and l'it's and	Values				
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}} I_{D} = 1 \text{mA}$		-	98.33	-	mV/°C	
Zero gate voltage drain current	I_{DSS} V_{DS} = 100V, V_{GS} = 0V		-	-	10	μA	
Gate - Source leakage current	I _{GSS}	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = 10V, I _D = 2.5mA	2.0	-	4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$			-8.28	-	mV/°C	
Static drain - source	D *4	V _{GS} = 10V, I _D = 50A	-	4.4	5.8		
on - state resistance	$R_{DS(on)}^{*4}$	V _{GS} = 6.0V, I _D = 40A	-	5.2	7.8	mΩ	
Gate resistance	R _G	R_G f = 1MHz, open drain		2.6	-	Ω	
Forward Transfer Admittance	Y _{fs} ^{*4}	V _{DS} = 5V, I _D = 40A	30	-	-	S	

*1 T_c =25°C, Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 L \simeq 0.10mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25°C Fig.3-1,3-2

*4 Pulsed



•Electrical characteristics (T_a = 25°C)

Deremeter	Cumphal	Conditions		Unit		
Parameter	Symbol	/mbol Conditions		Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	4170	-	
Output capacitance	C _{oss}	V _{DS} = 50V	-	590	-	pF
Reverse transfer capacitance	C _{rss}	C _{rss} f = 1MHz		130	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq 50V, V_{GS}$ = 10V	-	37	-	
Rise time	t _r *4	I _D = 50A	-	33	-	
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 1.0\Omega$	-	125	-	ns
Fall time	t _f *4	R _G = 10Ω	-	54	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumbol	ymbol Conditions		Values			1 1	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Tatal water channel 0 *4	O *4		V _{GS} = 10V	-	80.0	-		
Total gate charge	Q _g *4	$V_{DD} \simeq 50V$	$V_{DD} \simeq 50V$		-	51.0	-	nC
Gate - Source charge	Q _{gs} *4	I _D = 50A	V _{GS} = 6V	-	24.0	-	nc	
Gate - Drain charge	Q _{gd} *4			-	17.5	-		

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Deremeter	Symbol		Values			Unit
Parameter	Symbol	ymbol Conditions		Тур.	Max.	Unit
Continuous forward current	I _S	T _a = 25°C	-	-	120	А
Pulse forward current	I _{SP} *2	$T_a = 25 C$	-	-	240	А
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 40A	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 50A, V _{GS} =0V	-	67	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/µs	-	225	-	nC



1000

= 10ms

P

100

10/

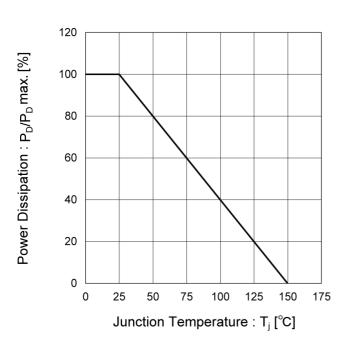


Fig.1 Power Dissipation Derating Curve

1000 1000 100 100 10 $P_{W} = 100\mu s$

Drain Current : I_D [A]

1

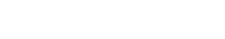
0.1

0.1

T_a=25°C Single Pulse

1

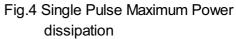
Fig.2 Maximum Safe Operating Area

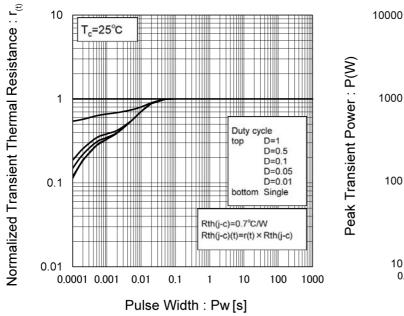


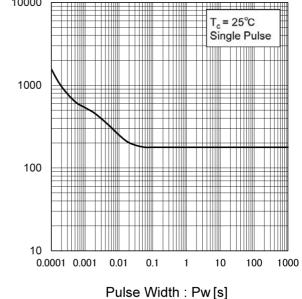
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Drain - Source Voltage : V_{DS} [V]

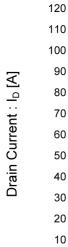
Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width











0

0

Fig.5 Typical Output Characteristics(I)

T_a=25°C

1

Pulsed

V_{GS}= 10V

V_{GS}= 6.0V

 $V_{GS} = 4.5V$

 $V_{GS} = 4.0V$

0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9

Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)

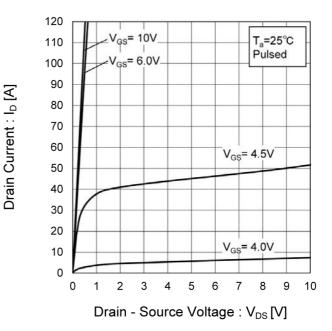
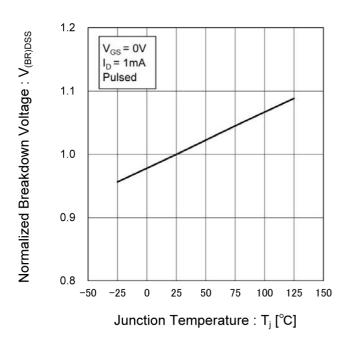


Fig.7 Breakdown Voltage vs. Junction Temperature







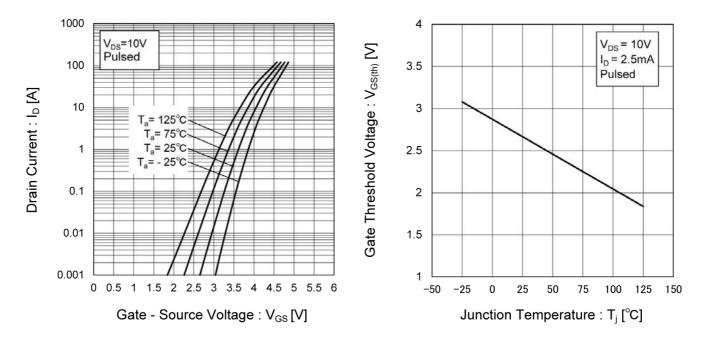
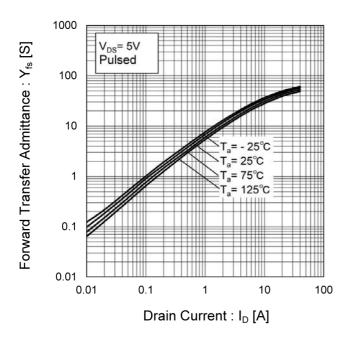


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

Fig.10 Forward Transfer Admittance vs. Drain Current







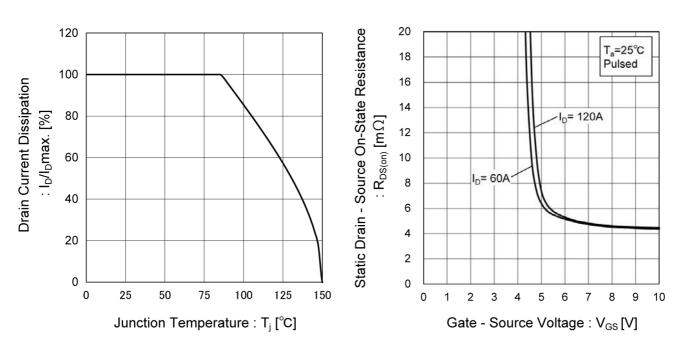
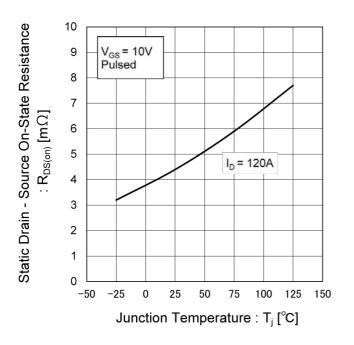


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







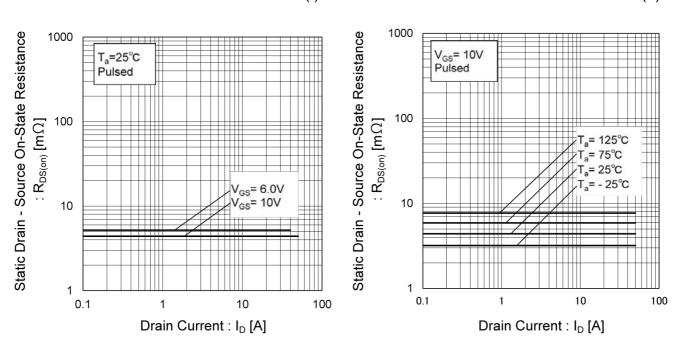
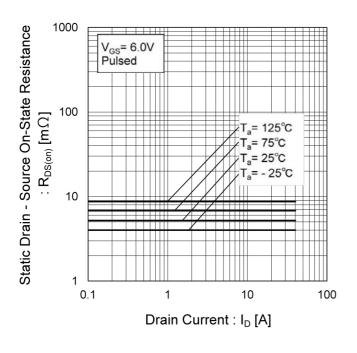


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)







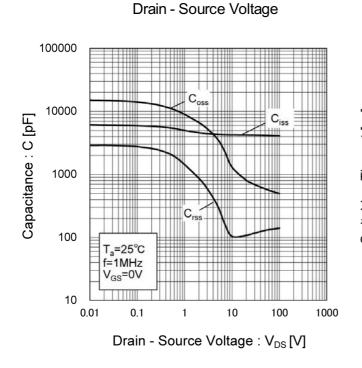


Fig.17 Typical Capacitance vs.

Fig.18 Switching Characteristics

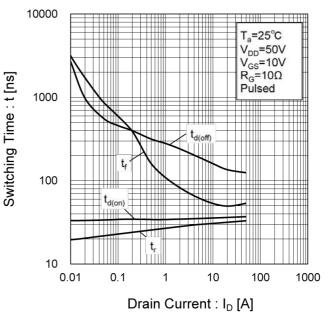


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V_{GS} [V]

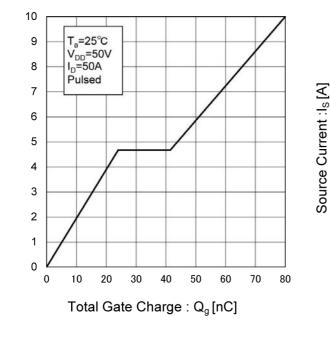
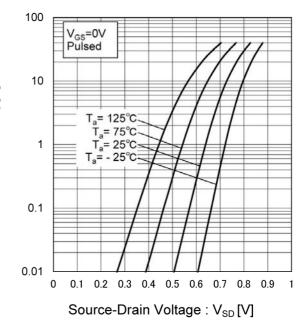


Fig.20 Source Current vs. Source Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

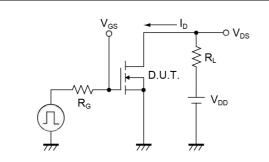


Fig.2-1 Gate Charge Measurement Circuit

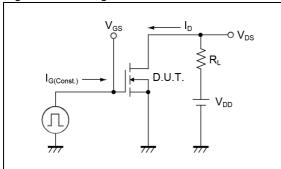


Fig.3-1 Avalanche Measurement Circuit

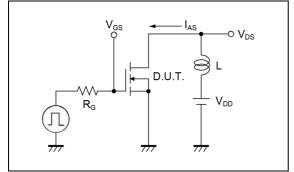


Fig.1-2 Switching Waveforms

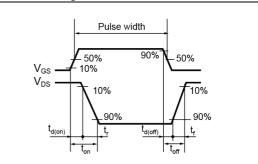


Fig.2-2 Gate Charge Waveform

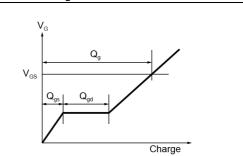
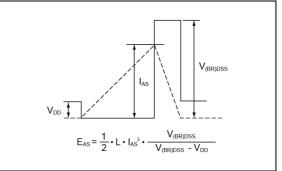
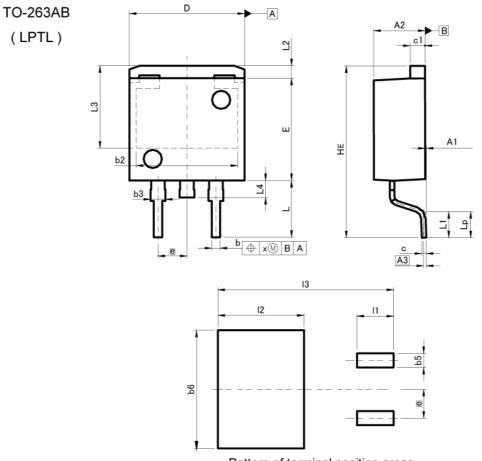


Fig.3-2 Avalanche Waveform





Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
e	2.5	54	0.1	00
HE	14.80	15.40	0.583	0.606
L	4.70	5.30	0.185	0.209
L1	2.10	2.70	0.083	0.106
L2	1.	10	0.043	
L3	7.1	7.25		85
L4	1.5	1,50		59
Lp	2.60	2.00	0.102	0.079
x	1	0.25	-	0.010
	MILIM	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b5	-	1.23	-	0.049
b6		10.40		0,409
11	1 	3.20		0.126
12	2 73	7.55	-	0.297
13	5 	15.40	-	0.606

Dimension in mm/inches



Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (^{Note 1)}, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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